

HSU276A Silicon Schottky Barrier Diode for Mixer

REJ03G0613-0200 (Previous: ADE-208-837A) Rev.2.00 Apr 28, 2005

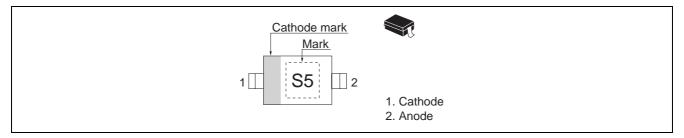
Features

- High forward current, Low capacitance.
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSU276A	S5	URP	PTSP0002ZA-A (URP)

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Repetitive peak reverse voltage	V _{RRM}	5	V
Reverse voltage	V _R	3	V
Average rectified current	lo	30	mA
Junction temperature	Тј	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

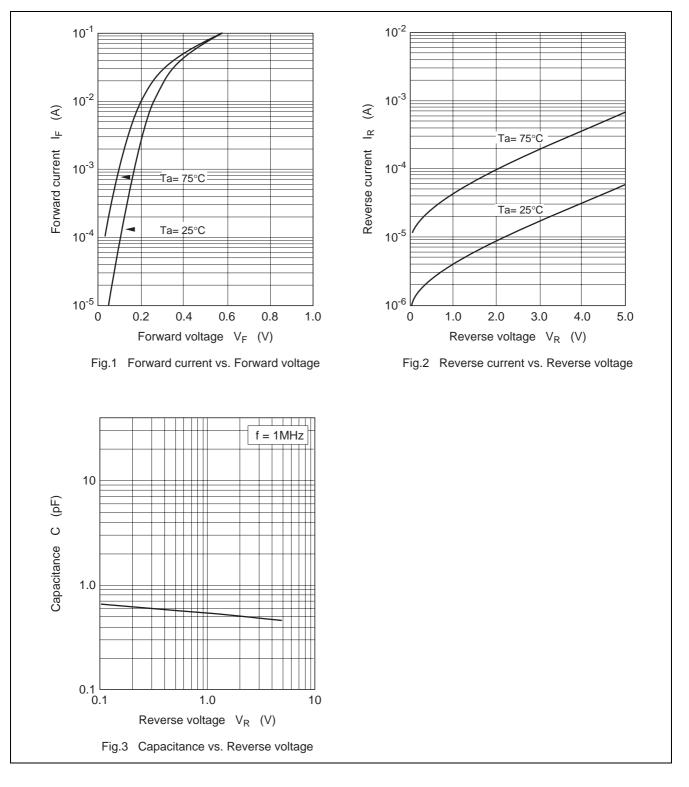
(Ta = 25°C)

ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V _R	3.0	-	—	V	I _R = 1 mA
Reverse current	I _R	_	-	50	μA	V _R = 0.5 V
Forward current	I _F	35	-	—	mA	V _F = 0.5V
Capacitance	С	_		0.85	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capability *	—	30	_	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Note: Failure criterion ; $I_R > 100 \ \mu A$ at V_R = 0.5 V

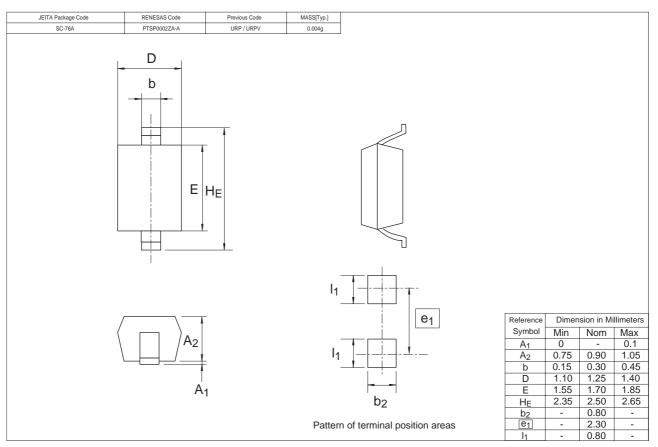


Main Characteristic





Package Dimensions





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